



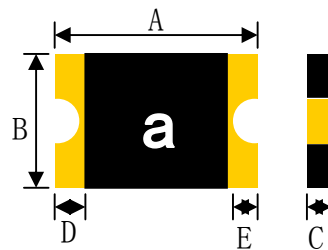
Shenzhen Wondhope Electric Co.,Ltd.

Add:2/F, Bldg 3, Minxing Industrial Zone, Minkang Rd, Minzhi Office, Longhua New Area, Shenzhen	package:	SMD 0805
	Model:	WH 005
	V _{max} :	16V
	I _{max} :	10A
Tel: 86-0755-29503668-8047	SS:	ROHS
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Email:sunny@wondhope.com P.C.:518131		

Specification Sheet

Marking :

a: Part identification



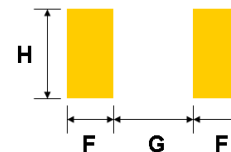
Appearance and size of production

Solderability:

Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3

Terminal Pad Materials:

Sn-plated nickel-copper, lead-free device.



Recommended pad layout

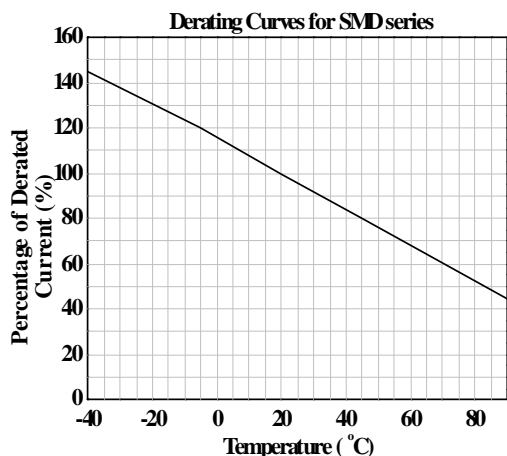
Dimensions:

UNIT	A		B		C		D	E	F	G	H
	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MIN			
mm	1.9	2.2	1.2	1.5	0.5	0.9	0.2	0.1	1	1.2	1.5
inch	0.075	0.087	0.047	0.059	0.020	0.040	0.010	0.004	0.04	0.050	0.060

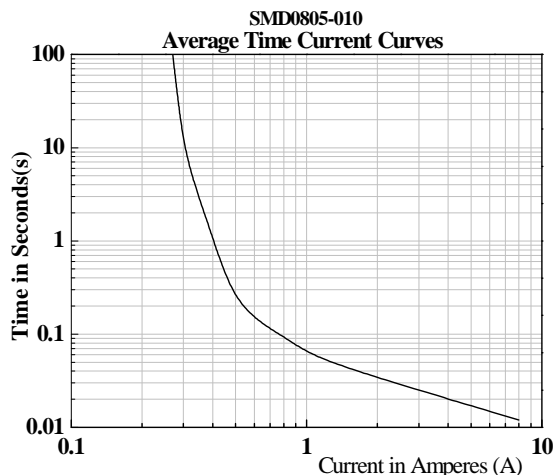
Performance Specification:

Model	V _{max} (V _{dc})	I _{max} (A)	I _{hold} @25°C (A)	I _{trip} @25°C (A)	P _d Tpy. (W)	Maximum Time To Trip		Resistance	
						Current (A)	Time (Sec)	R _i min (Ω)	R ₁ max (Ω)
SMD005	16	10	0.05	0.15	0.5	0.25	1.5	3.5	50
V _{max} : Maximum voltage , device can withstand without damage at rated current;									
I _{max} : Maximum fault current, device can withstand without damage at rated voltage;									
I _{hold} : Hold Current.,device will sustain for 30min without tripping in 25°C still air;									
I _{trip} : Minimum current at which the device will trip in 25°C still air;									
P _d : Power dissipated from device when in the tripped state in 25°C still air;									
R _i min: Minimum resistance of device in initial (un-soldered) state;									
R ₁ max: Maximum resistance of device at 25°C measured one hour post reflow.									

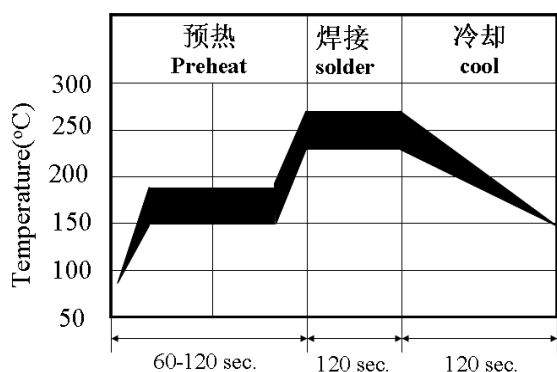
Average Time Current Curve



Average Time Current Curve at 25°C



Solder reflow conditions



Note: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

- 1、 Recommended reflow methods: IR, vapor phase oven, hot air oven.
- 2、 Devices are not designed to be wave soldered to the bottom side of the board.
- 3、 Recommended maximum paste thickness is 0.25 mm (0.010 inch).
- 4、 Devices can be cleaned using standard method and solvents.

Storage and Handling

Storage conditions: 30°C max, 60% R.H. Devices may not meet specified performance if storage conditions are exceeded.

Order Information

a=Part identification, SMD0805=Packaging, 005=Model
5000pcs/Reel

WARNING:

- 1、 Use PPTC exceed by the maximum rating and improper use may result in device damage and possible electrical arcing and flame.
- 2、 PPTC are designed for protection against over current or temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- 3、 Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- 4、 Use PPTC with a large inductance in circuit will generate a circuit voltage above the rated voltage of the PPTC.
- 5、 Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- 6、 If any quality problems caused by improper use mentioned above, our company is not responsible.